

BRCS20P06DPQ

Rev.B Feb.-2025

描述 / Descriptions

TO-252 塑封封装 P 沟道场效应管。
P-CHANNEL MOSFET in a TO-252 Plastic Package.

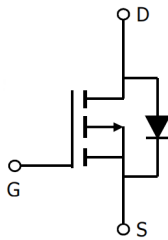
特征 / Features

$V_{DS} (V) = -60V$ $I_D = -20A (V_{GS} = \pm 20V)$
 $R_{DS(ON)} @ -10V \leq 75m\Omega (Typ. 62m\Omega)$
 $R_{DS(ON)} @ -4.5V \leq 100m\Omega (Typ. 70m\Omega)$
 符合 AEC-Q101 标准高可靠性要求，无卤产品。
 Qualified to AEC-Q101 Standards for High Reliability, HF Product.

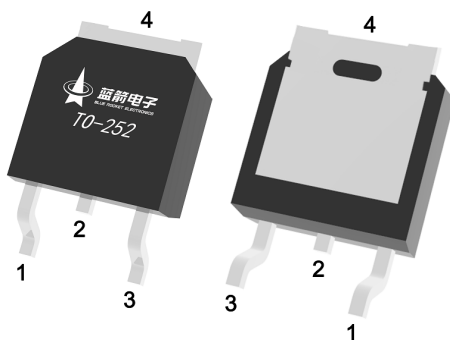
用途 / Applications

用于低压电路如：汽车电路、DC/DC 转换、便携式产品的电源高效转换，满足汽车应用的严格要求。
 Suited for low voltage applications such as automotive, DC/DC Converters, and high efficiency switching for power management in portable and battery operated products, Meet the stringent requirements of automotive applications.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN 1 : G PIN 2 : D PIN 3 : S PIN 4 : D

印章代码 / Marking

见印章说明。
See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Drain-Source Voltage	V _{DSS}	-60	V
Gate-Source Voltage	V _{GSS}	±20	V
Continuous Drain Current	I _D (T _c =25°C)	-20	A
Pulsed Drain Current	I _{DM}	-80	A
Avalanche Current	I _{AS}	-13.8	A
Avalanche energy L=0.5mH	E _{AS}	95	mJ
Power Dissipation for Single Operation	P _D (T _c =25°C)	45	W
Maximum Junction Temperature	T _j	150	°C
Storage Temperature Range	T _{stg}	-55 ~ 150	°C
Thermal Resistance-Junction to Ambient	R _{θJA}	50	°C/W
Thermal Resistance- Junction-to-Case	R _{θJC}	2.8	°C/W

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Drain-Source Breakdown Voltage	BV _{DSS}	I _D =-250μA V _{GS} =0V	-60	-69		V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-60V V _{GS} =0V			-1.0	
Gate-Body leakage current	I _{GSS}	V _{DS} =0V V _{GS} =±20V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} I _D =-250μA	-1.0	-1.5	-2.5	V
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =-10V I _D =-20A		62	75	mΩ
		V _{GS} =-4.5V I _D =-10A		70	100	
Diode Forward Voltage	V _{SD}	I _S =-1A V _{GS} =0V			-1.0	V
Input Capacitance	C _{iss}	V _{GS} =0V V _{DS} =-25V f=1MHz		1380		pF
Output Capacitance	C _{oss}			100		
Reverse Transfer Capacitance	C _{rss}			65		
Total Gate Charge	Q _{g(10V)}	V _{GS} =-10V V _{DS} =-30V I _D =-4A		20.8		nC
Total Gate Charge	Q _{g(4.5V)}			10.8		
Gate-Source Charge	Q _{gs}			3.5		
Gate-Drain Charge	Q _{gd}			3.6		

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Turn-on Delay Time	$t_{d(ON)}$	$V_{GS}=-10V$ $V_{DS}=-30V$ $R_L=7.5\Omega$ $R_{GEN}=3\Omega$		8		ns
Turn-on Rise Time	t_r			3.8		
Turn-off Delay Time	$t_{d(OFF)}$			31.5		
Turn-off Fall Time	t_f			7.5		

电参数曲线图 / Electrical Characteristic Curve

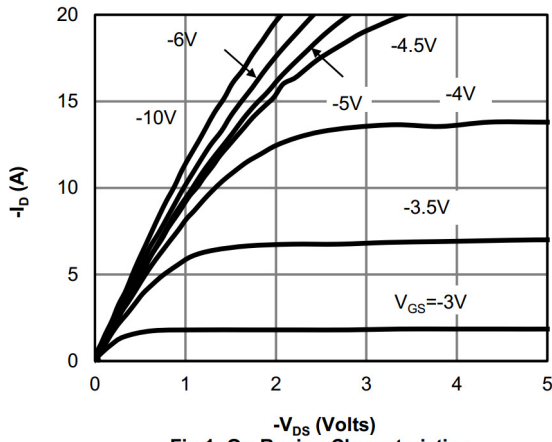


Fig 1: On-Region Characteristics

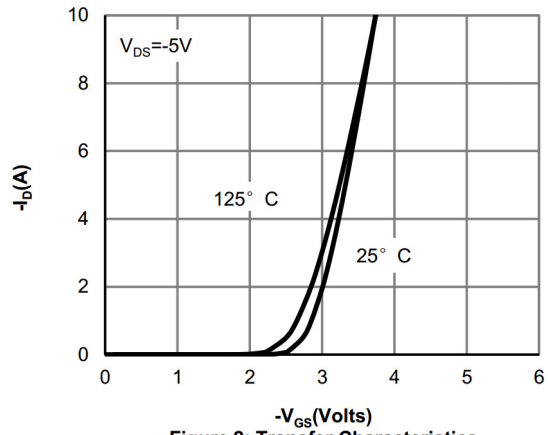


Figure 2: Transfer Characteristics

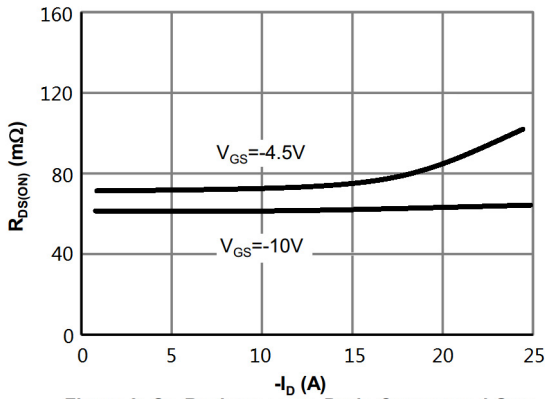


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

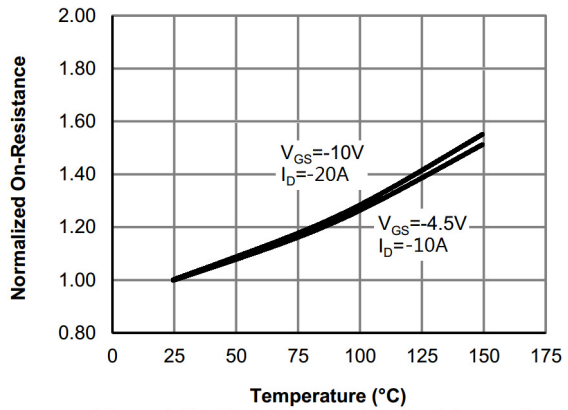


Figure 4: On-Resistance vs. Junction Temperature

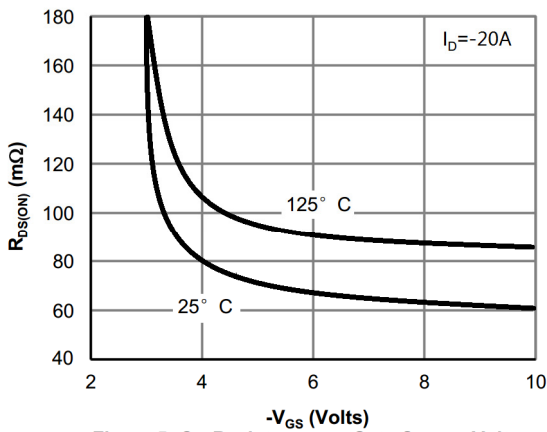


Figure 5: On-Resistance vs. Gate-Source Voltage

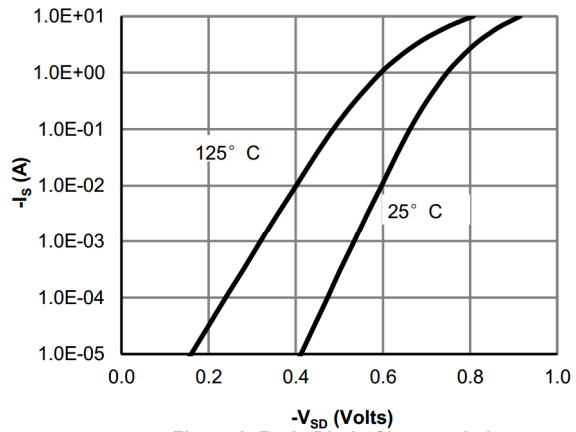


Figure 6: Body-Diode Characteristics

电参数曲线图 / Electrical Characteristic Curve

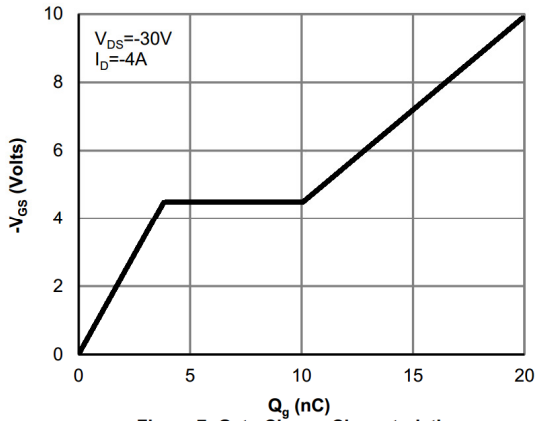


Figure 7: Gate-Charge Characteristics

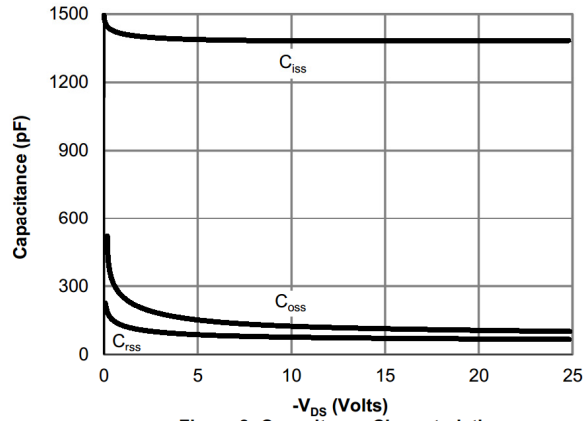


Figure 8: Capacitance Characteristics

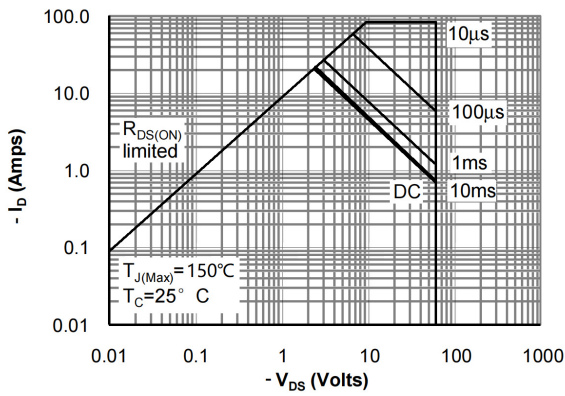


Figure 9: Maximum Forward Biased Safe Operating Area

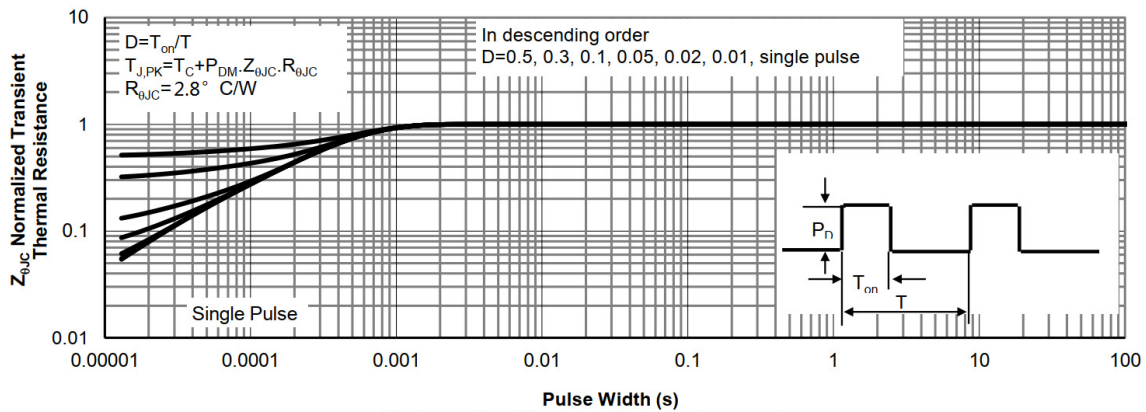
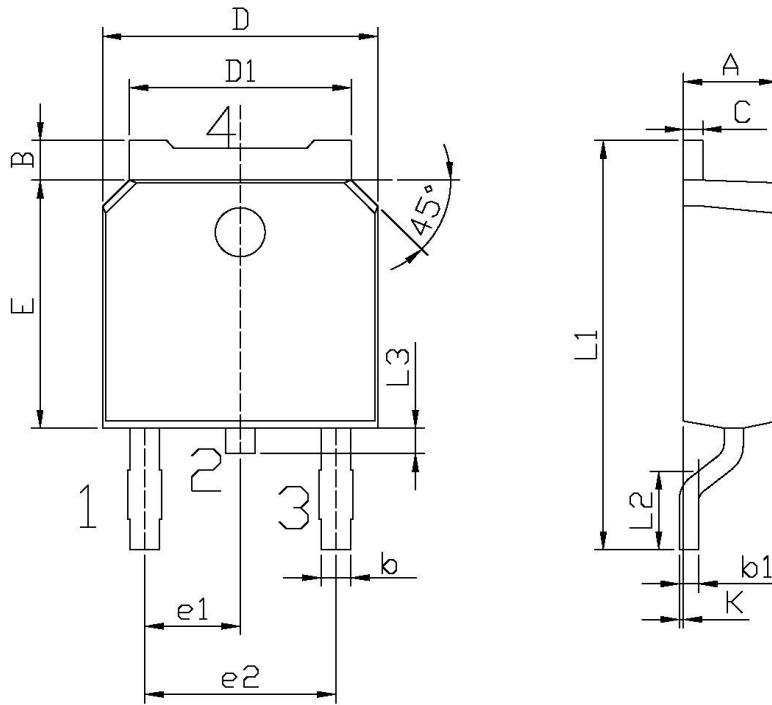


Figure 10: Normalized Maximum Transient Thermal Impedance

外形尺寸图 / Package Dimensions

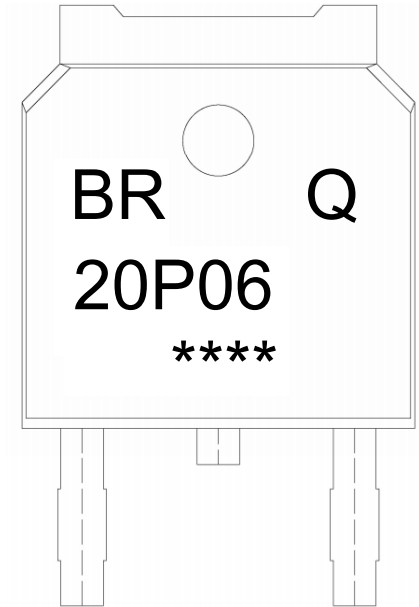


单位: mm

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	2.20	2.40	E	5.95	6.25
B	0.95	1.25	e1	2.24	2.34
b	0.70	0.90	e2	4.43	4.73
b1	0.45	0.55	L1	9.85	10.35
C	0.45	0.55	L2	1.70	2.00
D	6.45	6.75	L3	0.60	0.90
D1	5.10	5.50	K	0.00	0.10

TO-252

印章说明 / Marking Instructions



说明：

BR： 为公司代码

Q： 为汽车无卤产品标识

20P06： 为型号代码

****： 为生产批号代码，随生产批号变化

Note:

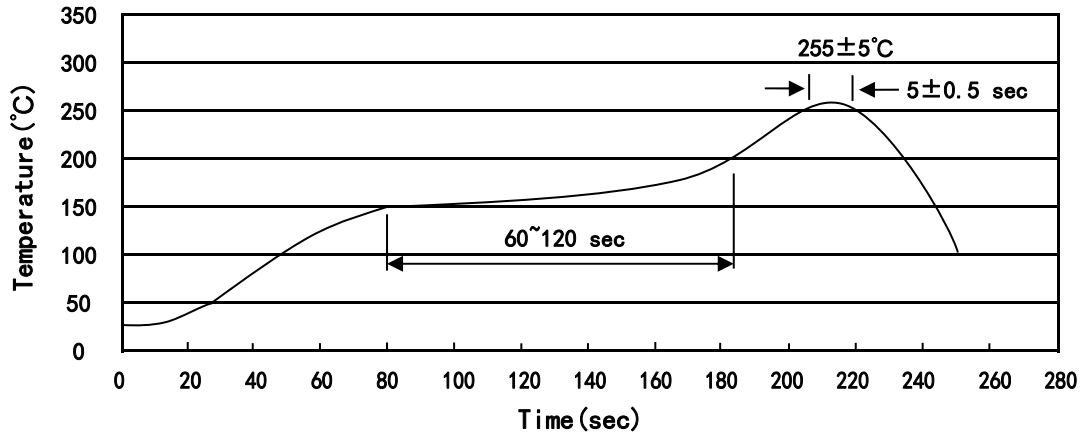
BR: Company Code

Q: Automobile halogen-free product Code

20P06: Product Type Code

****: Lot No. Code, code change with Lot No

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 150~200°C，时间 60~120sec;
- 2、峰值温度 255±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:150~200°C, Time:60~120sec.
- 2.Peak Temp.:255±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
TO-252	2,500	2	5,000	6	30,000	13" ×16	360×360×50	380×335×366

套管包装 / TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱
TO-251/252	75	48	3,600	5	18,000	526×20.5×5.25	555×164×50	575×290×180

使用说明 / Notices